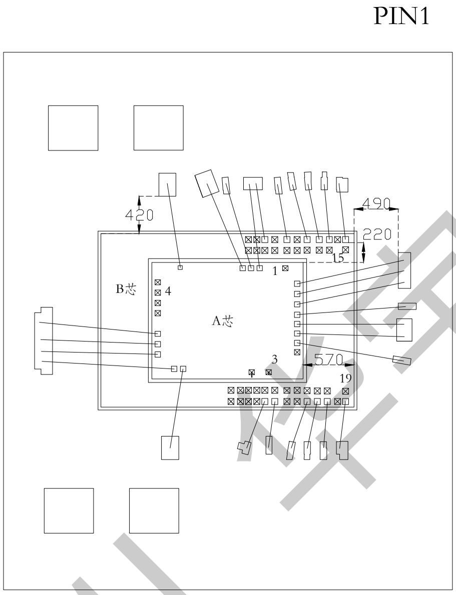
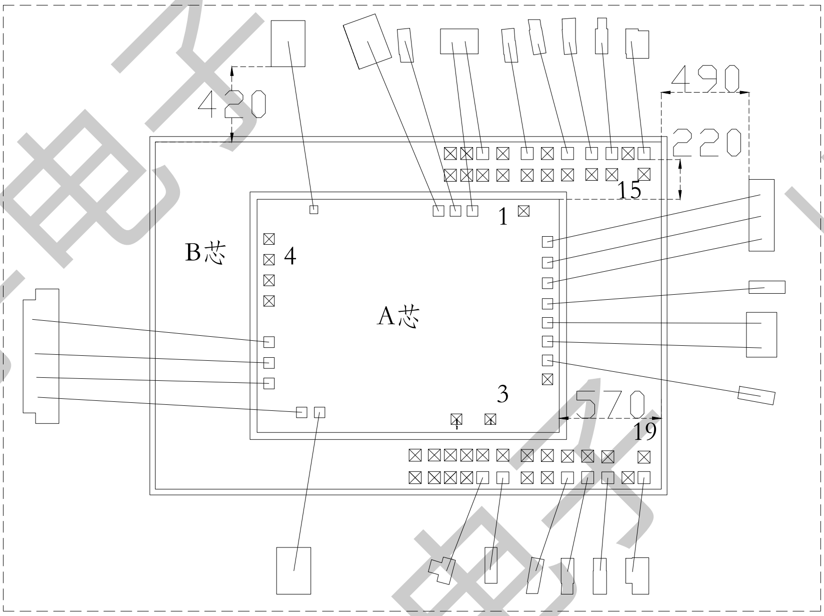
池州华宇电子科技股份有限公司
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

焊线图纸 Bonding Diagram

客户代码 Customer No.		线图号 Drawing No.			页码 Page 1 / 3	
产品名称 Product Type			封装外型 PKG Type	LGA8L(5×6×1.31-P1.27)		

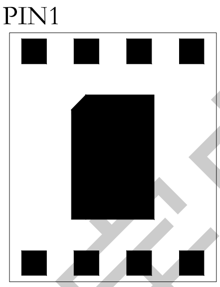
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
金丝 Au	18			1473	517	首选(Preferred)：G760L TypeA 备选(Optional)：	
客户图号 Customer drawing NO.							





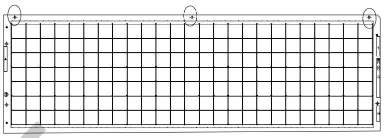
WB放大示意图

注意：A芯使用DAF



底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：上侧三个圆孔



实物图：
Chip photo：

特殊说明 Special Instructions：

DB注意：
1.装片位置公差为±30um；
2.控制溢胶，为WB预留焊线位置；避免溢胶到finger。

WB注意：
数字为不打线pad点个数。

说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPO (μm²)	最小焊盘间距 Min BPP(μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否是Low-K If low-k ?	减薄厚度(μm) Wafer Thickness
A芯： DIE A	绝缘胶DAF (Non-conductive) HR-5104		1300*1685(μm²) 51.18*66.34(mil²)	45*45	105	3.8	是/YES	80	NA	否/N0	200
B芯： DIE B	导电胶 (conductivity) 2100A		1935*2822.4μm²) 76.18*111.12(mil²)	67.5*67.5	90	1.4	是/YES	62	12	是/55nm	160
C芯： DIE C											

拟制 Prepared by		制图日期 Create Date		生效日期 Effective Date		客户确认签字/盖章： Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

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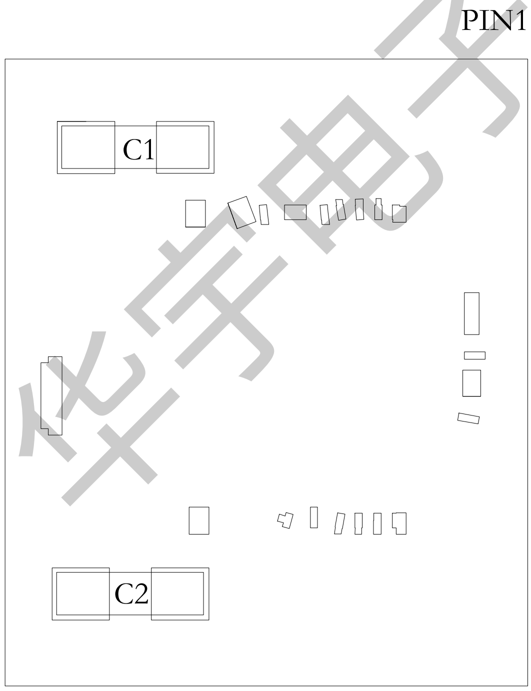
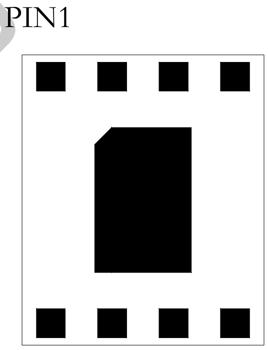
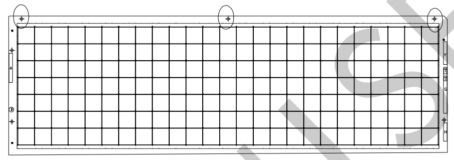




底部示意图

框架传送方向（装片）： L/F Direction（D/A）：上侧三个圆孔	实物图： Chip photo：	特殊说明 Special Instructions： SMT注意： 1.控制溢锡，防止沾锡。



NO.	Item	Reference	value	package	KD P/N	Quantity
1	贴片电容C1、C2		25V 1UF ±10% X5R	0402		2
2	基板	substrate	基板	/		1
3	锡膏	/	F590 SnCu0.7-89M4	/		/
SMT元器件总计						2

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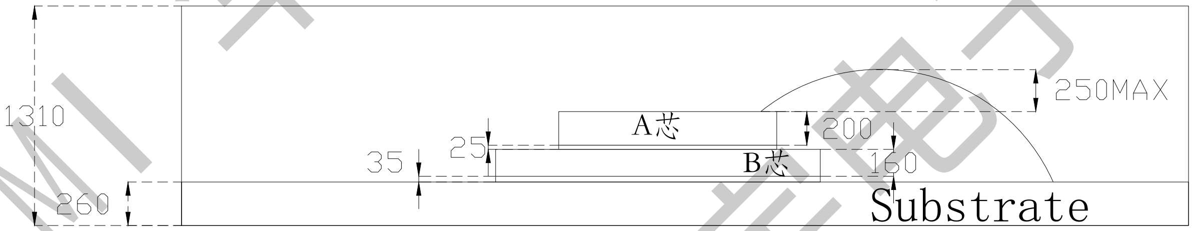

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